

**AMENDMENTS TO THE CLAIMS:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**LISTING OF CLAIMS:**

1. (Original) A surface protecting adhesive film for a semiconductor wafer in which an adhesive layer is formed on one surface of a base film, wherein the adhesive layer comprises 100 weight parts of a polymer (A) having a functional group capable of reacting with a cross-linking agent and a temperature (Ta) in a range of from -50°C to 5°C at which  $\tan \delta$  of a dynamic viscoelasticity of the polymer(A) is maximized , from 10 weight parts to 100 weight parts of a polymer (B) having a functional group capable of reacting with a cross-linking agent and a temperature (Tb) in a range of from more than 5°C to 50°C at which  $\tan \delta$  of a dynamic viscoelasticity of the polymer(B) is maximized , and from 0.1 weight part to 10 weight parts of a cross-linking agent (C) having two or more cross-linkable functional groups in a molecule based on 100 weight parts of total amount of the polymers (A) and (B), wherein the thickness of the adhesive layer is from 5  $\mu\text{m}$  to 50  $\mu\text{m}$ .

2. (Original) The surface protecting adhesive film for the semiconductor wafer according to claim 1, wherein a storage elastic modules ( $E'$ ) at 25°C of at least one layer of a base film is from  $1 \times 10^8$  to  $1 \times 10^{10}$  Pa and thickness of the base film is from 10  $\mu\text{m}$  to 120  $\mu\text{m}$ .

3. (Currently Amended) The surface protecting adhesive film for the semiconductor wafer according to ~~claim 1 or~~ claim 2, wherein polymers (A) and (B) are acrylic acid alkyl ester copolymers.

4. (Currently Amended) A protecting method for a semiconductor wafer comprising the steps of: applying a surface protecting adhesive film for the semiconductor wafer on a circuit-forming surface of the semiconductor wafer via an adhesive layer thereof; grinding a non-circuit-formed surface of the semiconductor wafer; and peeling away the surface protecting adhesive film for the semiconductor wafer, wherein the surface protecting adhesive film for the semiconductor wafer according to claim [[1 to]] 3 is used in the protecting method for the semiconductor wafer.

5. (New) The surface protecting adhesive film for the semiconductor wafer according to claim 1, wherein polymers (A) and (B) are acrylic acid alkyl ester copolymers.

6. (New) A protecting method for a semiconductor wafer comprising the steps of: applying a surface protecting adhesive film for the semiconductor wafer on a circuit-forming surface of the semiconductor wafer via an adhesive layer thereof; grinding a non-circuit-formed surface of the semiconductor wafer; and peeling away the surface protecting adhesive film for the semiconductor wafer, wherein the surface protecting adhesive film for the semiconductor wafer according to claim 5 is used in the protecting method for the semiconductor wafer.

7. (New) A protecting method for a semiconductor wafer comprising the steps of: applying a surface protecting adhesive film for the semiconductor wafer on a circuit-forming surface of the semiconductor wafer via an adhesive layer thereof; grinding a non-circuit-formed surface of the semiconductor wafer; and peeling away the surface protecting adhesive film for the semiconductor wafer , wherein the surface protecting adhesive film for the semiconductor wafer according to claim 2 is used in the protecting method for the semiconductor wafer.

8. (New) A protecting method for a semiconductor wafer comprising the steps of: applying a surface protecting adhesive film for the semiconductor wafer on a circuit-forming surface of the semiconductor wafer via an adhesive layer thereof; grinding a non-circuit-formed surface of the semiconductor wafer; and peeling away the surface protecting adhesive film for the semiconductor wafer , wherein the surface protecting adhesive film for the semiconductor wafer according to claim 1 is used in the protecting method for the semiconductor wafer.